Y H

Item And Code No.

I T E M	CONNECTOR
S P E C	1.25㎜ Pitch Wire to Board SMD Type
M A K E R S P E C	
Code No.	

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Specification Approval Sheet

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Pitch	1.25 mm
Special	Wire to Board
Type	SMD

12507 Series

Connector 제품규격
Product Specification

Indemnification

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● 제,개정 이력『History Revision』

NO	DATE	ISS.	CHK.	APP.	SUMMARY
1	2014.03.05	L.J.H	Y.M.K	C.G.N	Presentation
2	2014.03.27	L.J.H	Y.M.K	C.G.N	웨이퍼 : 4 ~ 6pin 형상 추가

아래와 같이 사양 승인원을 제출합니다.

『Yeon Ho Electronics CO.,LTD. submits the approval certification of connector specification.』

1. 업 체 명 : (주) 연 호 전 자
   『Manufactured by : Yeon Ho Electronics CO.,LTD.』
2. 기 안 부 서 : 품질관리실
   『Written by : Quality Control Department』

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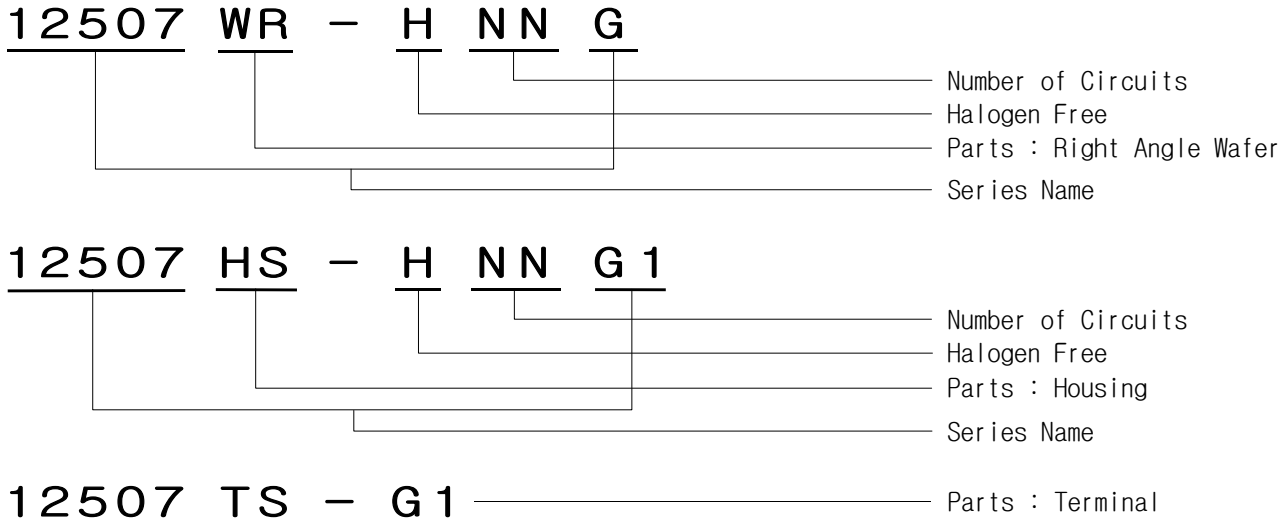
6. Q.C 공정도 『QC Process Chart』

1. 적용 범위 『Scope』

본 사양서는 (주)연호전자 제품 12507 series SMD type connector에 한하여 적용한다.
『This specification covers the requirements for 12507 series SMD type connector』

2. 형명 구성 『Numbering System of Products(Ordering Information of Products)』



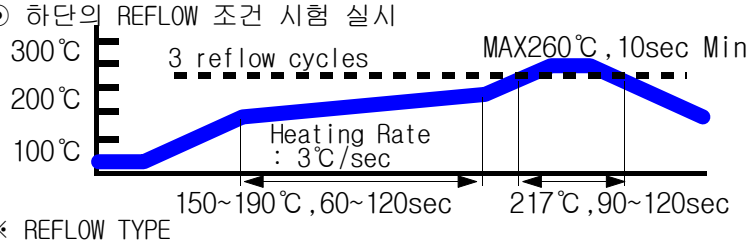
3. 원재료 『Material』

Item	Material	Grade	Maker	Over plated / Color
Wafer Material	LCP	E130i	Polyplastics	Black
Housing Material	PA66	GN1001BF	LG Chem	White
Pin Material	Phosphor Bronze	C5191	Poong San	* Under plating : Ni(1.3-3㎛) * Over plating : Sn(2-6㎛)
Hook Material	Brass	C2680	Poong San	* Under plating : Ni(1.3-3㎛) * Over plating : Sn(2-6㎛)
Terminal Material	Phosphor Bronze	C5210	Poong San	* Over plating : Pre-plated tin(1-2㎛)

4. 정 격 『Ratings』

항 목 (Item)	정 격 (Standard Data)
정격 전압 (Operating Voltage)	AC/DC 125V
정격 전류 (Current Rating)	AC/DC 1A
사용 온도 (Operating Temperature)	-25℃ ~ +85℃
적용 전선 (Applicable Wire)	AWG #26 ~ #32
적용 PCB (Applicable P.C.B)	0.8 ~ 1.6 mm

5. 성 능 『Performance Characteristics』

NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
1.	외 관 치 수 『Dimensions 』		첨부 제품도에 준한다. 『Refer to drawings』
2.	전 기 적 성 능 『Electrical Characteristics』		
	2-1.절연저항	⦿ 인접 Terminal(Contact)간에 DC 500V ±5V 전압을 1분±5초간 인가하였을 때 절연저항을 측정한다. (1회 측정에서 규격 치 미달인 경우 3시간 이내 재측정)	100MΩ 이상
	2-1.Insulation Resistance	⦿ Measured between adjacent contacts ⦿ Test voltage : DC 500V ±5V / 1 min ±5 sec (Based upon MIL-STD-202G Method 302 Condition B)	100MΩ MIN
	2-2.내 전 압	⦿ 인접한 Terminal간에 AC 250V 전압을 1분±5초간 인가한다. ⦿ 누설전류 : 2.0 mA	절연파괴 및 섬락이 없고 사용상 결함이 없을 것.
	2-2.Dielectric Withstanding Voltage	⦿ Measured between adjacent contacts ⦿ Test voltage : AC 250V / 1 min ±5 sec ⦿ Leakage current : 2.0 mA (Based upon MIL-STD-202G Method 301)	No flash over and no physical damage shall be observed
	2-3.접촉저항	⦿ Terminal과 Wafer Pin간의 접촉저항 측정	30mΩ 이하
	2-3.Contact Resistance	⦿ Measured the resistance of mated connector,20mV.10mA	30mΩ MAX
3.	물 리 적 성 질 『Physical Characteristics』		
	3-1.납 땜 성	⦿ FLUX (ROSIN 10%, METHANOL 90%)에 5~10초 동안 담근 후 SnAg(3.5)Cu(0.7)의 Pot 납땜조 온도 (240℃±5℃)에 3초 ±0.5초 동안 침전시킨다.	침전 부위의 납땜이 90% 이상일 것
	3-1.Solder Ability	⦿ Immersion in flux consisting of rosin 10% and methanol 90% for a period of 5 to 10 seconds dip in molten solder consisting of SnAg(3.5)Cu(0.7) at 240℃ plus or minus 5 degrees for 3 plus or minus 0.5 seconds.	More than 90% of area dipped in molten solder should be coated by solder
	3-2.납땜내열성	※ REFLOW TYPE ⦿ 하단의 REFLOW 조건 시험 실시 	외관 변형등이 없을 것
	3-2.Solder Heat Resistance	※ REFLOW TYPE ⦿ The connector shell be tested resistance, to soldering heat in the following conditions. The temperature shall be measured on the surface of P.C.B	Appearance : Good
	3-3.Pin유지력	⦿ 사출물(수지)이 Pin을 유지하고 있는 힘 측정 * Pin을 25±3mm/min 속도로 뺄 때의 힘을 측정한다.	0.5 ~ 3.0Kgf
	3-3.Pin Retention Force	⦿ Measured withdrawal force that resin grips and supports pin * Velocity of withdrawal : 25 ±3mm/min	

NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
	3-4.단일삽입력 3-4.Single Insertion Force	⊙ 1개의 Terminal에 1개의 Pin을 삽입 할 때의 힘 측정 ⊙ Measured force to insert single pin into single terminal.	0.1 ~ 0.7Kgf
	3-5.단일발거력 3-5.Single Withdrawal Force	⊙ 1개의 Terminal로부터 1개의 Pin을 뺄 때의 힘 측정 ⊙ Measured force to withdrawal single pin into single Terminal.	0.05 ~ 0.6Kgf
	3-6.총합삽입력1 3-6.Total Insertion Force1	⊙ 회로수가 같은 Housing Ass`Y에 Wafer Ass`Y를 삽입할 때의 힘 측정 (Unlocking) ⊙ Measured force to insert wafer assembly into the housing assembly which has same circuits (Unlocking)	1.0 ~ 8.0kgf
	3-7.총합삽입력2 3-7.Total Insertion Force2	⊙ 회로수가 같은 Housing Ass`Y에 Wafer Ass`Y를 삽입할 때의 힘 측정 (Locking) ⊙ Measured forces to insert wafer assembly into the housing assembly which has same circuits (Locking)	1.0 ~ 8.0kgf
	3-8.총합발거력1 3-8.Total Withdrawal Force1	⊙ 결합된 Housing Ass`Y로부터 Wafer Ass`Y를 발거할 때의 힘 측정 (Unlocking) ⊙ Measured forces to withdraw wafer assembly from the housing assembly which has same circuits (Unlocking)	1.0 ~ 8.0kgf
	3-9.총합발거력2 3-9.Total Withdrawal Force2	⊙ 결합된 Housing Ass`Y로부터 Wafer Ass`Y를 발거할 때의 힘 측정 (Locking) ⊙ Measured forces to withdraw wafer assembly from the housing assembly which has same circuits (Locking)	2.5 ~ 10.0kgf
	3-10.내구성시험 3-10.Durability of Contact Resistance	⊙ 결합된 제품 Housing Ass`Y과 Wafer Ass`Y의 삽입 및 분리 동작을 10회/분 속도로 30회 행한 후 접촉저항 측정. ⊙ Measured contact resistance after 30 cycles of total insertion and withdrawal operation. ⊙ Withdrawal Rate : 10th/min.	below 20% compared with the initial measured value.
	3-11.Terminal 삽입력 3-11.Insertion Force of Terminal	⊙ Housing을 고정시키고 Terminal를 25 ±3㎜/min 속도로 일직선으로 삽입할 때의 삽입력 측정. ⊙ Insert a terminal into the housing straightly and measure insertion force ⊙ Velocity of insertion : 25 ±3mm/min	0.05 ~ 0.5Kgf
	3-12.Terminal 조립강도 3-12.Terminal Retention Force	⊙ Housing에 Terminal을 조립한 후 Terminal을 25 ±3㎜/min 속도로 인장시켜 이탈될 때의 힘 측정 ⊙ Insert a terminal into the housing and measure the force to withdraw the terminal from housing. ⊙ Apply axial pull out force at the speed rate of 25 ±3mm/minute	0.5 ~ 4.0kgf
	3-13.압착강도 3-13.Crimp Tensile Strength	⊙ Terminal에 Lead Wire를 압착한후 압착부위(심선부위)가 파괴될 때까지 25 ±3㎜/min 속도로 인장강도 측정 ⊙ Measured tensile strength of the crimped contact (stripped wire barrel section of contact) to conductor joint	AWG #26 : 1.5Kgf MIN AWG #28 : 1.0Kgf MIN AWG #30 : 0.8Kgf MIN AWG #32 : 0.5Kgf MIN

NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
	3-14.Terminal Gap 변화량 3-14.Terminal Gap Variation	⦿ Terminal의 삽입 및 분리 동작을 10회/분 속도로 30회 행한 후 Gap 변화량을 측정 ⦿ Measured terminal gap variation after 30 cycles of terminal insertion and withdrawal operation ⦿ Withdrawal rate : 10th/min	below 20% compared with the initial terminal gap.
	3-15.단일삽입력 변화량 3-15.Single Insertion Force Variation	⦿ Terminal의 삽입 및 분리 동작을 10회/분 속도로 30회 행한 후 단일삽입력 변화량을 측정 ⦿ Measured single insertion force variation after 30 cycles of terminal insertion and withdrawal operation ⦿ Withdrawal rate : 10th/min	below 50% compared with the initial measured value.
	3-16.단일발거력 변화량 3-16.Single Withdrawal Force Variation	⦿ Terminal의 삽입 및 분리 동작을 10회/분 속도로 30회 행한 후 단일발거력 변화량을 측정 ⦿ Measured single withdrawal force variation after 30 cycles of terminal insertion and withdrawal operation ⦿ Withdrawal rate : 10th/min	below 50% compared with the initial measured value.
4.	환 경 시 험 『Environmental Test』		
	4-1.내진동성 시 험	⦿ DC 100mA 통전상태에서 진폭1.52mm 진동수 10-55-10HZ 진동 상태에서 X,Y,Z방향으로 각각 2시간씩 진동을 시킨 후 단전상태 및 접촉저항 측정	1)단전상태: 1μsec 동안 단전상태 없을 것 2)접촉저항: 30mΩ이하 3)내전압: 절연파괴 및 섬락이 없고 사용상 결함이 없을 것 4)절연저항: 100MΩ 이상 5)총합 삽입력 : 1.0 ~ 8.0kgf 5)총합 발거력 : 1.0 ~ 8.0kgf
	4-1.Vibration	⦿ Current of 100mA shall be applied during the testing The vibration shall be along each axis for the period of two hours with the maximum amplitude of 1.52mm and frequency of 10-55-10Hz/Min (Based upon MIL-STD-202G Method 201A)	1)Discontinue : 1μsec MAX 2)Contact Resistance : 30mΩMAX 3)Dielectric Strength : No flash over and no physical damage shall be observed 4)Insulation Resistance : 100MΩ MIN 5)Total Insertion Force : 1.0 ~ 8.0kgf 6)Total Withdrawal Force : 1.0 ~ 8.0kgf
	4-2.전압변동률 4-2.Voltage Variation	⦿ DC 5V 커넥터를 병렬로 연결한 상태에서, 진폭 1.52mm, 진동수 10-55-10Hz, X,Y 방향으로 각각 2시간씩 진동을 시킨 후 전압 변화량 및 변화 지속 시간 확인. ⦿ Checking the current variation and duration, after vibrating it two hours with the condition under 1.52mm of amplitude, 10-55-10Hz of frequency , and parallel connection with DC 5V connector.	5V ±5% 이하 5V ±5% MAX

NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
	4-3.염수분무 시 험	⊙ Connector를 결합한 상태에서 아래 조건으로 시험 후 흐르는 물에 세척후 상온에서 2시간 방치 후에 특성을 측정한다. 조건: 염수농도 5% ±1% 염수분무 시간 48시간 ±4시간 8시간 분무 16시간 휴지 2Cycles 시험온도 35℃ ±2℃	1)접촉저항: 30mΩ이하 2)내전압: 절연파괴 및 섬락이 없고 사용상 결함이 없을 것 3)절연저항: 100MΩ 이상 4)총합 삽입력 : 1.0 ~ 8.0kgf 5)총합 발거력 : 1.0 ~ 8.0kgf 6)외관: 흑녹현상 없을것
	4-3.Salt Spray	⊙ Measure after exposure to salt solution spray of 5 ±1% density at a temperature of 35℃ ±2℃ for 48hrs ±4hrs - Spray 8hrs and Pause 16hrs, 2Cycles after test wash and leave to dry for 2hrs. (Based upon MIL-STD-202G Method 101E Condition B)	1)Contact Resistance : 30mΩMAX 2)Dielectric Strength : No flash over and no physical damage shall be observed 3)Insulation Resistance : 100MΩ MIN 4)Total Insertion Force : 1.0 ~ 8.0kgf 6)Total Withdrawal Force : 1.0 ~ 8.0kgf 6)Appearance : Not black rust
	4-4.내습성시험	⊙ Connector를 결합한 상태에서 아래조건에 따라 시험을 행한 후 측정한다. 조건 : 시험조의 온도 40℃ ±2℃ 상 대 습 도 90% ~ 95% 시 험 시 간 96시간	1)접촉저항: 30mΩ이하 2)내전압: 절연파괴 및 섬락이 없고 사용상 결함이 없을 것 3)절연저항: 100MΩ 이상 4)총합 삽입력 : 1.0 ~ 8.0kgf 5)총합 발거력 : 1.0 ~ 8.0kgf 6)외관 : 양호할 것
	4-4.Humidity	⊙ Mated connector shall be left for 96 hours in an environment of 40 ±2℃, and 90 ~ 95% humidity. After the exposure the connector shall be left in an ambient condition for one hour before the measurement is done (Based upon MIL-STD-202G Method 103B Condition B)	1)Contact Resistance : 30mΩ MAX 2)Dielectric Strength : No flash over and no physical damage shall be observed 3)Insulation Resistance : 100MΩ MIN 4)Total Insertion Force : 1.0 ~ 8.0kgf 6)Total Withdrawal Force : 1.0 ~ 8.0kgf 6)Appearance : Good

NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
	4-4.내고온성 시 험	⊙ Connector를 결합한 상태에서 시험조의 온도 85 ±2℃에서 96시간 동안 시험 후 상온에서 30분간 방치 후 측정한다.	1)접촉저항: 30mΩ 이하 2)절연저항: 100MΩ 이상 3)내전압: 절연파괴 및 섬락이 없고 사용상 결함이 없을 것 4)총합 삽입력 : 1.0 ~ 8.0kgf 5)총합 발거력 : 1.0 ~ 8.0kgf
	4-4.Resistance to High Temperature	⊙ Chamber temperature : 85 ±2℃ Exposed 30 minutes after being exposed 96 hours under the chamber temperature electrical characteristics were measured and tested (Based upon MIL-STD-202G Method 108A Condition A)	1)Contact Resistance : 30mΩ MAX 2)Insulation Resistance : 100MΩ MIN 3)Dielectric Strength : No flash over and no physical damage shall be observed 4)Total Insertion Force : 1.0 ~ 8.0kgf 6)Total Withdrawal Force : 1.0 ~ 8.0kgf
	4-5.내한성시험	⊙ Connector를 결합한 상태에서 시험조의 온도 -40 ±3℃에서 96시간 동안 시험 후 상온에서 30분간 방치 후 측정한다.	1)접촉저항: 30mΩ 이하 2)절연저항: 100MΩ 이상 3)내전압: 절연파괴 및 섬락이 없고 사용상 결함이 없을 것 4)총합 삽입력 : 1.0 ~ 8.0kgf 5)총합 발거력 : 1.0 ~ 8.0kgf
	4-5.Altitude Low Temperature	⊙ Chamber temperature : -40 ±3℃ Exposed 30 minutes after being exposed 96 hours under the chamber temperature electrical characteristics were measured and tested (Based upon JIS C60068-2-1)	1)Contact Resistance : 30mΩ MAX 2)Insulation Resistance : 100MΩ MIN 3)Dielectric Strength : No flash over and no physical damage shall be observed 4)Total Insertion Force : 1.0 ~ 8.0kgf 6)Total Withdrawal Force : 1.0 ~ 8.0kgf

<table>
<tr><th>NO.</th><th>시험항목
『Test Title』</th><th>시 험 방 법 및 조 건
『Test Procedures/Methods Conditions』</th><th>규 격
『Requirements』</th></tr>
<tr><td></td><td>4-6.열충격시험</td><td>⊙ Connector를 결합한 상태에서 아래조건에 따라 5회 연속 시험을 행한 후 시험을 실시한다.
<table>
<tr><td>단 계</td><td>1</td><td>2</td><td>3</td><td>4</td></tr>
<tr><td>온도(℃)</td><td>-55 +0 -3</td><td>25 +10 -5</td><td>85 +3 -0</td><td>25 +10 -5</td></tr>
<tr><td>시간(분)</td><td>30</td><td>5</td><td>30</td><td>5</td></tr>
</table></td><td>1)접촉저항: 30mΩ 이하
2)절연저항: 100MΩ 이상
3)내전압: 절연파괴 및 섬락이 없고 사용상 결함이 없을 것
4)총합 삽입력 : 1.0 ~ 8.0kgf
5)총합 발거력 : 1.0 ~ 8.0kgf
6)외관 : 양호할 것</td></tr>
<tr><td></td><td>4-6.Thermal Shock</td><td>⊙ Mated connector shall be exposed five cycles as table #1 (Based upon MIL-STD-202G Method 107-A table #1)
<table>
<tr><td>STEP</td><td>1</td><td>2</td><td>3</td><td>4</td></tr>
<tr><td>Temperature (℃)</td><td>-55 +0 -3</td><td>25 +10 -5</td><td>85 +3 -0</td><td>25 +10 -5</td></tr>
<tr><td>Exposed Time (MIN)</td><td>30</td><td>5</td><td>30</td><td>5</td></tr>
</table></td><td>1)Contact Resistance : 30mΩ MAX
2)Insulation Resistance : 100MΩ MIN
3)Dielectric Strength : No flash over and no physical damage shall be observed
4)Total Insertion Force : 1.0 ~ 8.0kgf
5)Total Withdrawal Force : 1.0 ~ 8.0kgf
6)Appearance : Good</td></tr>
</table>

6. 포장 및 식별방법 『Identification and Packing』

1) 포장 조건 『Packing Condition』 : Bulk Packing

2) 수 량 『Quantity』

3) 포장 방법 『Packing Method』 :

충분한 강도의 종이 BOX를 사용하여 충격을 방지하여 물리적 변형 또는 화학적 변화가 발생되지 않도록 하여야 한다.

『 Carton box for shipment must have enough strength in order to protect physical damage during transportation.』

4) 식별 표시 : 다음과 같은 사항을 제품포장 BOX에 명기한다.

『Identifications shall be marked as follows』

4-1. 제조회사, 제조자명 또는 상표 『Manufacture's LOGO』

4-2. 형명 또는 부품번호 『Part Number』

4-3. 수 량 『Quantity』

4-4. 제조 LOT NO 『Date Code』

4-5. 기타 상호 필요하다고 인정되는 사항

『Others agreed with manufacturer and customer』

7. 사용상 주의사항 『Caution for Use』

본 connector는 강(强)Lock 사양이므로, Connector 감합후의 Wire Harness의 부정확한 취급방향이나 과도하게 잡아당길 경우에는 납땜부의 파괴, Lock등 Connector자체의 파괴 또는 실장기판의 파괴등 Trouble를 발생시킬 가능성이 있습니다.
이와 같은 Trouble을 미연에 방지하고, Connector 성능을 충분히 내기 위해서는, Wire Harness를 취급할 때 다음과 같은 주의를 바랍니다.

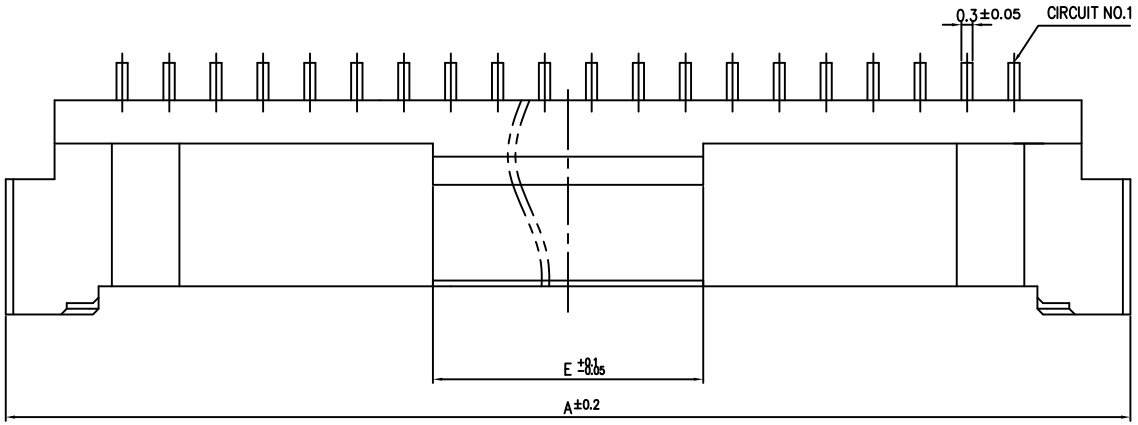
『This connector is secure lock type, so the connector must be treated with care after mated. Incorrect handling direction and excessive pulling load to the wire harness may cause troubles which affect its performances such as degradation at solder tail, breakage of connector itself (lock devise, etc.) and a PCB for mounting. To prevent these troubles and make full use of connector's performances, special care should be taken on the following points when handling the wire harness.』

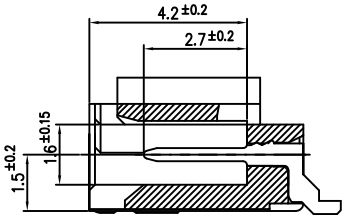
1) Connector에는 평소 Wire Harness 취급할 때, 인장하중 이외에 외력을 지속적으로 가하지 않는다.
『Do not apply an external force to a connector continuously except for pulling load and so on when handling wire harness as usual.』

2) 전선에는 Connector의 삽발작업이 무리없이 이루어 질 수 있도록 “느슨하게” 설계하고 삽발작업은 감합축 선으로 한다.
『For the wire, make an appropriate looseness to mate and unmate the connector on the mating axis without strain.』

3) Connector에서 Wire Harness를 분리할 때에는 Lock을 완전히 해제하고 발거한다.
『When withdraw wire harness from the connector, Lock should be unlocked perfectly and withdraw.』

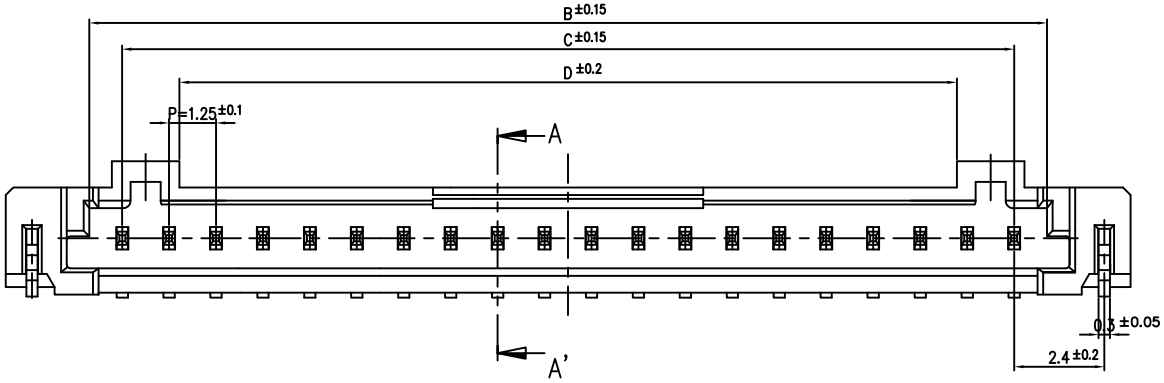
출도일	/ /	연구소

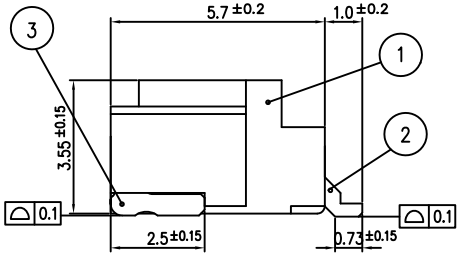


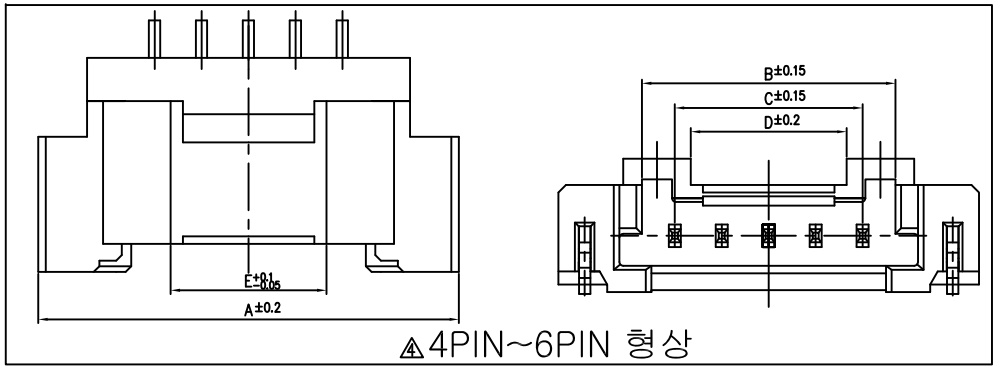


SECTION A-A'

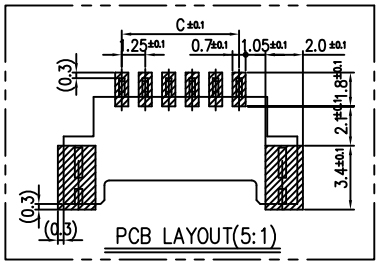
PARTS NO.	A	B	C	D	△2 E
12507WR-H04G	9.95	5.5	3.75	3.05	3.0
12507WR-H05G	11.2	6.75	5.0	4.15	3.5
12507WR-H06G	12.45	8.0	6.25	5.4	3.5
12507WR-H07G	13.7	9.25	7.5	4.45	4.0
12507WR-H08G	14.95	10.5	8.75	5.7	△3 4.3 ~~4.0~~
12507WR-H09G	16.2	11.75	10.0	6.95	△3 4.3 ~~4.0~~
12507WR-H10G	17.45	13.0	11.25	8.2	△3 4.3 ~~4.0~~
12507WR-H11G	18.7	14.25	12.5	9.45	△3 4.3 ~~4.0~~
12507WR-H12G	19.95	15.5	13.75	10.7	△3 4.3 ~~4.0~~
12507WR-H13G	21.2	16.75	15.0	11.95	7.2
12507WR-H14G	22.45	18.0	16.25	13.2	7.2
12507WR-H15G	23.7	19.25	17.5	14.45	7.2
12507WR-H16G	24.95	20.5	18.75	15.7	7.2
12507WR-H17G	26.2	21.75	20.0	16.95	7.2
12507WR-H18G	27.45	23.0	21.25	18.2	7.2
12507WR-H19G	28.7	24.25	22.5	19.45	7.2
12507WR-H20G	29.95	25.5	23.75	20.7	7.2
12507WR-H21G	31.2	26.75	25.0	21.95	7.2
12507WR-H22G	32.45	28.0	26.25	23.2	7.2
12507WR-H23G	33.7	29.25	27.5	24.45	7.2
12507WR-H24G	34.95	30.5	28.75	25.7	7.2
12507WR-H25G	36.2	31.75	30.0	26.95	7.2
12507WR-H26G	37.45	33.0	31.25	28.2	7.2
12507WR-H27G	38.7	34.25	32.5	29.45	7.2
12507WR-H28G	39.95	35.5	33.75	30.7	7.2
12507WR-H29G	41.2	36.75	35.0	31.95	7.2
12507WR-H30G	42.45	38.0	36.25	33.2	7.2







△4 4PIN~6PIN 형상



PCB LAYOUT(5:1)

NOTE
1. MATING PARTS:
PIN = 12507PR-G
HOOK = 35002LR-F
HOUSING = 12507HS-HNNG
12507HS-NNL,HNNG1,HNNL3

I/NO	DESCRIPTION	MATERIAL	QTY	REMARK
3	HOOK	Brass	2	Tin-plated
2	PIN	Phosphor bronze	NN	Tin-plated
1	WAFER	LCP	1	UL94V-0

LTR	REVISION RECORD	DATE	DR	CHK
△4	4PIN~6PIN 형상 추가	14.03.26	K.Y.M	J.J.H
△3	"E"치수 4.0에서 4.3으로 수정(08P~12P)	11.08.19	K.Y.M	K.J.K
△2	"E"치수 표기	10.12.28	K.Y.M	S.H.K
△1	관리치수 및 공차 추가	10.12.02	K.K.S	S.H.K

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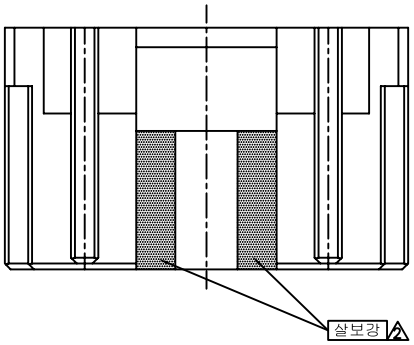
YEONHO ELECTRONICS CO., LTD.

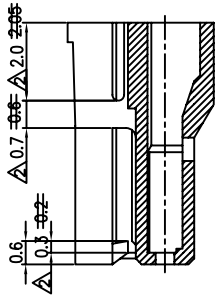
TITLE: 12507WR-HNNG

SCALE	DRAWN	DESIGN	CHECK	APPD
10/1	10.01.29 K.K.S		10.01.29 J.J.H	10.01.29 Y.Y.W

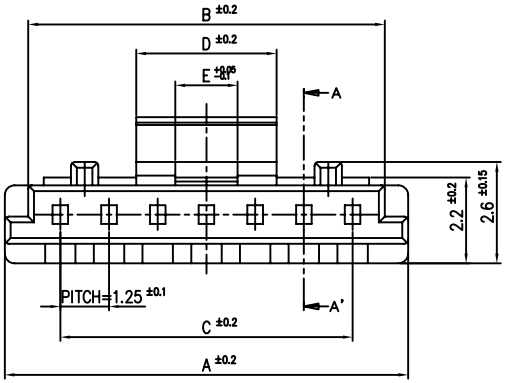
SIZE A2 | 12507WR-H00G-S | REV 04

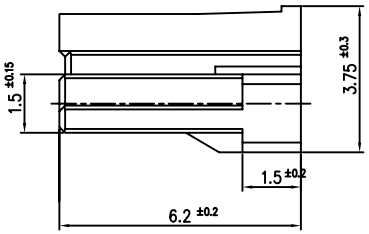
PARTS NO.	A	B	C	D	△1 E
√ 12507HS-H04G1	6.6	5.4	3.75	2.6	1.4
√ 12507HS-H05G1	7.85	6.65	5.0	3.6	2.0
√ 12507HS-H06G1	9.1	7.9	6.25	3.6	2.0
√ 12507HS-H07G1	10.35	9.15	7.5	3.6	2.0
√ 12507HS-H08G1	11.6	10.4	8.75	5.0	3.0
√ 12507HS-H09G1	12.85	11.65	10.0	5.0	3.0
√ 12507HS-H10G1	14.1	12.9	11.25	5.0	3.0
12507HS-H11G1	15.35	14.15	12.5	5.0	3.0
√ 12507HS-H12G1	16.6	15.4	13.75	5.0	3.0
12507HS-H13G1	17.85	16.65	15.0	9.0	6.2
√ 12507HS-H14G1	19.1	17.9	16.25	9.0	6.2
√ 12507HS-H15G1	20.35	19.15	17.5	9.0	6.2
12507HS-H16G1	21.6	20.4	18.75	9.0	6.2
12507HS-H17G1	22.85	21.65	20.0	9.0	6.2
12507HS-H18G1	24.1	22.9	21.25	9.0	6.2
12507HS-H19G1	25.35	24.15	22.5	9.0	6.2
√ 12507HS-H20G1	26.6	25.4	23.75	9.0	6.2
12507HS-H21G1	27.85	26.65	25.0	9.0	6.2
√ 12507HS-H22G1	29.1	27.9	26.25	9.0	6.2
12507HS-H30G1	39.1	37.9	36.25	9.0	6.2

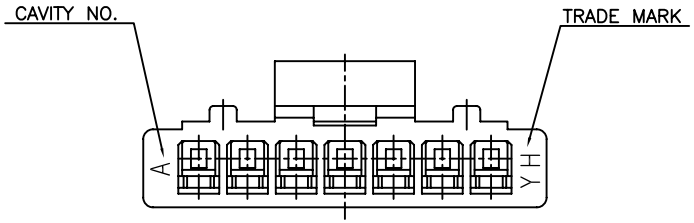


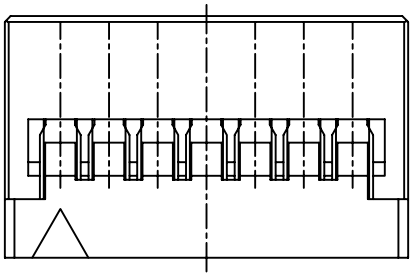


SECTION A-A'









NOTE:
1. MATING PART:
   - TERMINAL= 12507TS-G1
   - WAFER = 12507WR-HNNG

△2	LOCK부 체결력 강화(표시부 살보강)	11.05.25	K.Y.M	K.J.K
△1	"E"치수 표기	10.12.28	K.Y.M	S.H.K
LTR	REVISION RECORD	DATE	DR	CHK

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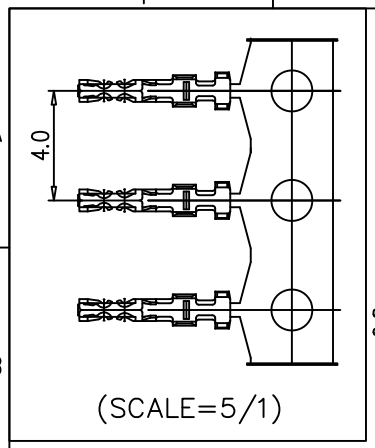
	HOUSING	PA66	1	UL94V-0
I/NO	DESCRIPTION	MATERIAL	QTY	REMARK

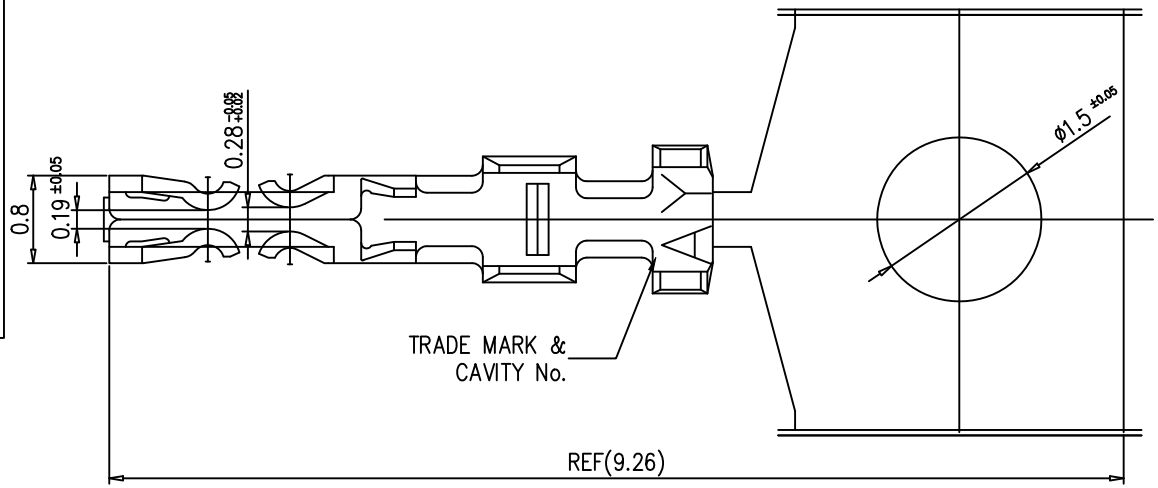
YEONHO ELECTRONICS CO., LTD.

TITLE: 12507HS-HNNG1

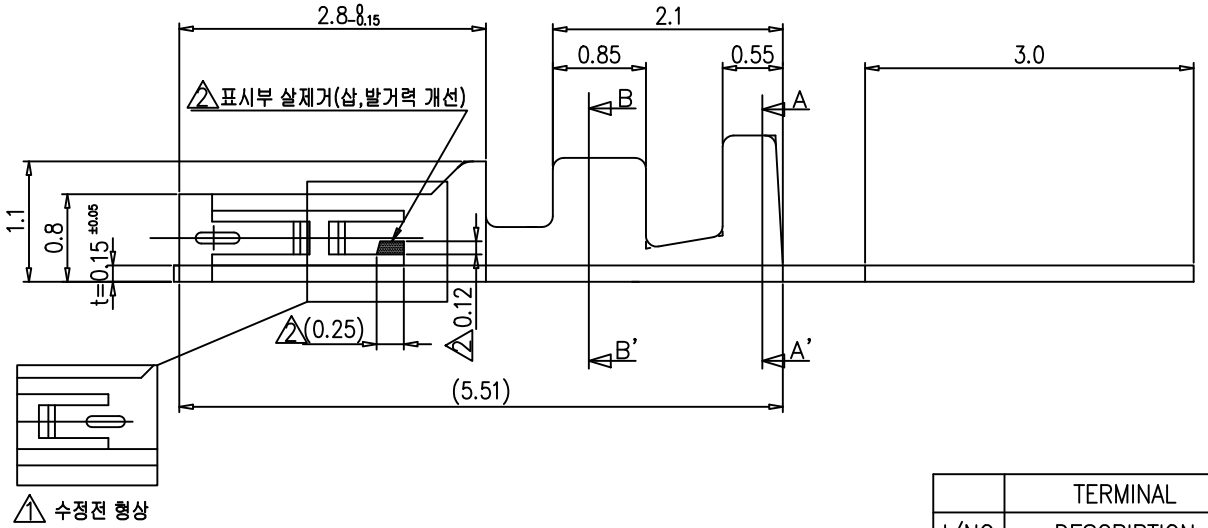
SCALE	DRAWN	DESIGN	CHECK	APPD
10/1	10.10.28 K.Y.M		10.10.28 J.J.H	10.10.28 S.H.K

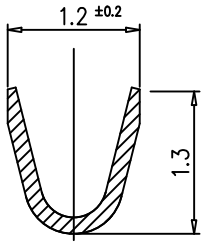
SIZE	DWG. NO	REV
A2	12507HS-H00G1-S	02



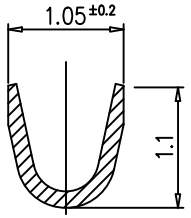


NOTES.
1. 일반공차: ±0.2
2. 사용전선 : AWG #26~#32
3. INSULATION DIA Ø1.35 ~ Ø1.0
4. MATING PART
: HOUSING - 12507HS-HNNG1





SECTION A-A



SECTION B-B

	TERMINAL	PHOSPHOR BRONZE		Tin-Plated
I/NO	DESCRIPTION	MATERIAL	QTY	REMARK

YEONHO ELECTRONICS CO., LTD.

TITLE: 12507TS-G1

SCALE	DRAWN	DESIGN	CHECK	APPD
20/1	L.S.H 2010. 10. 28		J.J.H 2010. 10. 28	

SIZE: A3 | DWG. NO: 12507TS-G1-S | REV: 02

LTR	REVISION RECORD	DATE	DR	CHK
2	삽,발거력 개선(표시부 살제거)	12.01.27	K.Y.M	C.S.W
1	삽입력 개선(2차 삽입부 bead 제거)	11.01.25	L.S.H	J.J.H